

Claims

What is Claimed is:

1. A method for mounting through an adhesive sheet an electronic component on a printed board provided with a wiring pattern comprising the steps of:

heating air intervening between the adhesive sheet and the printed board; and
bonding the adhesive sheet to an area of the printed board to be mounted with the electronic component in the above state.

2. The method for mounting the electronic component according to claim 1, wherein the air intervening between the adhesive sheet and the printed board is heated upon heating the printed board.

3. The method for mounting the electronic component according to claim 2, wherein the electronic component is thermally bonded on the adhesive sheet after the printed board bonded with the adhesive sheet is cooled down.

4. The method for mounting the electronic component according to claim 1, wherein the heating temperature is set to not less than 60 degrees Celsius nor more than reaction temperature of the adhesive sheet.

5. The method for mounting the electronic component according any one of claim 1, claim 2, claim 3, and claim 4, wherein the adhesive sheet is defined as an anisotropic conductive film.

6. The method for mounting the electronic component according to any one of claim 1, claim 2, claim 3, and claim 4, wherein the printed board is defined as a flexible board.